

## PATENT ABSTRACTS OF JAPAN

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### (54) MANUFACTURE OF HIGH ELECTROMAGNETIC WAVE SHIELDING COMPOSITE SHEET

(57)Abstract:

PROBLEM TO BE SOLVED: To integrate a conductive fiber material with a resin matrix layer in the layer at a desired position without breaking the conductive fiber material, by depressurizing a deposited layer of conductive short fiber and a resin matrix film layer, and forming a conductive fiber-resin integrated layer.

SOLUTION: A resin matrix layer is formed by applying a resin film containing polymer material as a main component on to a sheetlike base substance 1. In at

least one surface-side surface layer part of a resin matrix layer formed on this sheetlike base substance 1, a

deposited laminar substance of a specified quantity of conductive short fiber is buried, and a conductive fiber-resin integrated layer 2 is formed by it. In the formation

of the conductive fiber-resin integrated layer like this, conductive short fiber is distributed with a high density only in the surface layer part of at least one surface of the resin matrix layer, forming a deposited laminar substance. It does not matter if conductive short fiber is not



distributed in the remaining part of the resin matrix layer partically, or is distributed with a high density practically over the whole volume.